

EL ALFS Series

ALFS4J-C010001H-AM



Features

- Package : SMD ceramic package
- Typ. Luminance Flux : 1700 lm @ 1000mA
- Viewing angle : 120°
- ESD : up to 8KV
- MSL : 2
- Qualifications : According to AEC-Q102
- Sulfur robustness : Class A1
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Applications

- Automotive Exterior Lighting
- Headlamp
- Daytime running light (DRL)
- Fog lamp

Contents

1. Characteristics	3
2. Absolute Maximum Ratings	4
3. Characteristics Graph	5
4. Binning Information	10
5. Part Number.....	14
6. Ordering Information	15
7. Mechanical Dimension.....	16
8. Recommended Soldering Pad.....	17
9. Reflow Soldering Profile	18
10. Packaging Information.....	19
11. Precaution for Use	21
12. Sulfur Test Criteria	22

1.Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Current ^[4]	I _F	50	1000	1500	mA	---
Luminous Flux ^{[1][2]}	Φ _v	1500	1700	2000	lm	I _F =1000mA
Forward Voltage ^[3]	V _F	11.6	13	15.2	V	I _F =1000mA
Viewing Angle	φ	---	120	---	deg	I _F =1000mA
Color	K	5391	---	6893	K	I _F =1000mA
Thermal Resistance (Junction to Solder)	R _{th JS real}	---	1.26	1.6	K/W	I _F =1000mA
	R _{th JS el}	---	0.8	1		

Notes:

- 1. Luminous Flux measurement tolerance: ±8%.
- 2. The data of Luminous Flux measured at thermal pad=25°C
- 3. Forward voltage measurement tolerance: ±0.05V
- 4. Current pulse time: 25ms

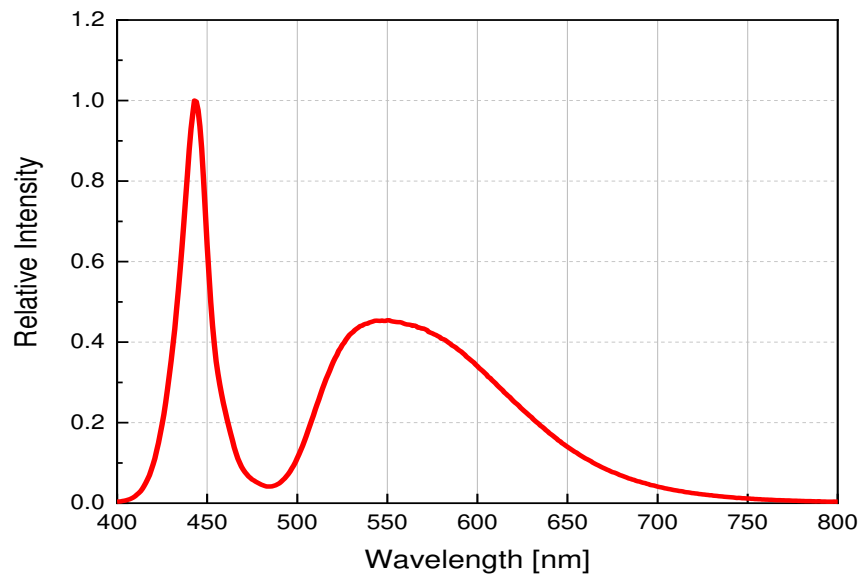
2. Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Power Dissipation	P_d	22800	mW
Forward Current	I_F	1500	mA
Reverse Voltage	V_R	Not designed for reverse operation	V
Junction Temperature	T_J	150	°C
Operating Temperature	T_{opr}	-40 ~ +125	°C
Storage Temperature	T_{stg}	-40 ~ +125	°C
ESD Sensitivity (R=1.5k Ω , C= 100pF)	ESD_{HBM}	8	kV
Soldering Temperature	Reflow	260	°C

3. Characteristics Graph

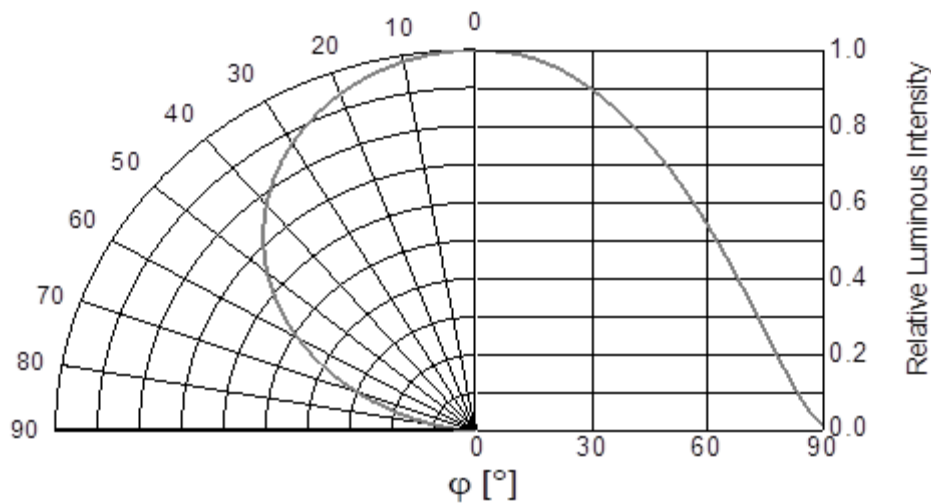
Wavelength Characteristics Relative Spectral Distribution
 @ Ts = 25°C, If=1000mA

$$\Phi_v / \Phi_v (Max.) = f(\lambda)$$



Typical Diagram Characteristics of Radiation

$$\Phi_v / \Phi_v (0^\circ) = f(\varphi)$$



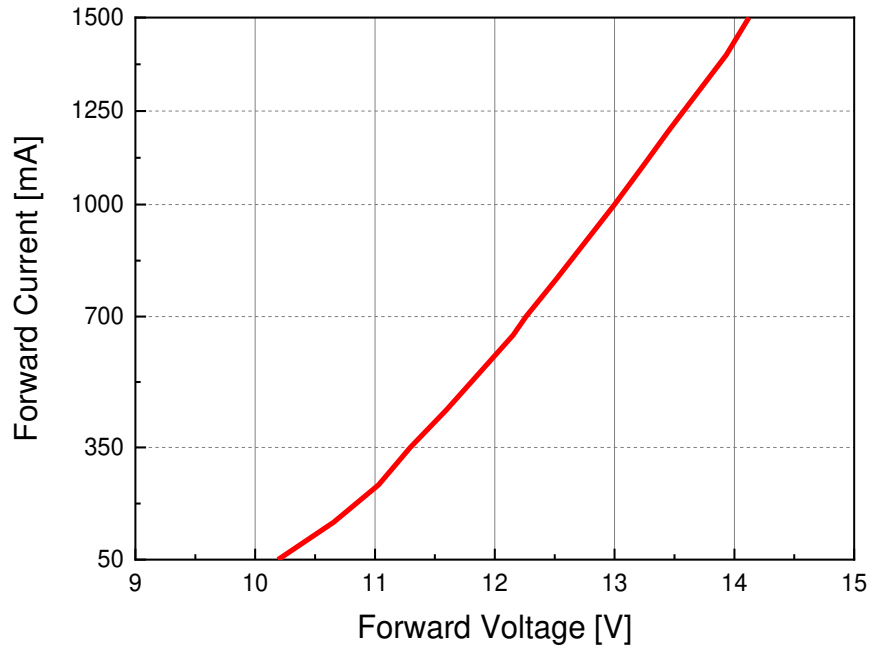
Notes:

1. φ is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
2. View angle tolerance is ± 5°.

Forward Current vs. Forward Voltage

@ Ts = 25°C

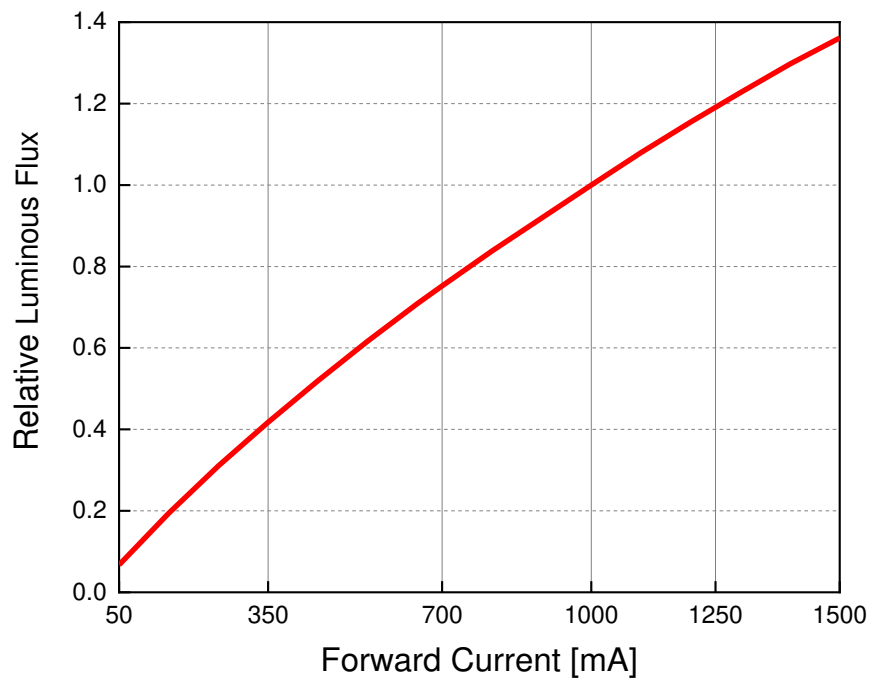
$$I_F = f(V_F)$$



Relative Luminous Intensity vs. Forward Current

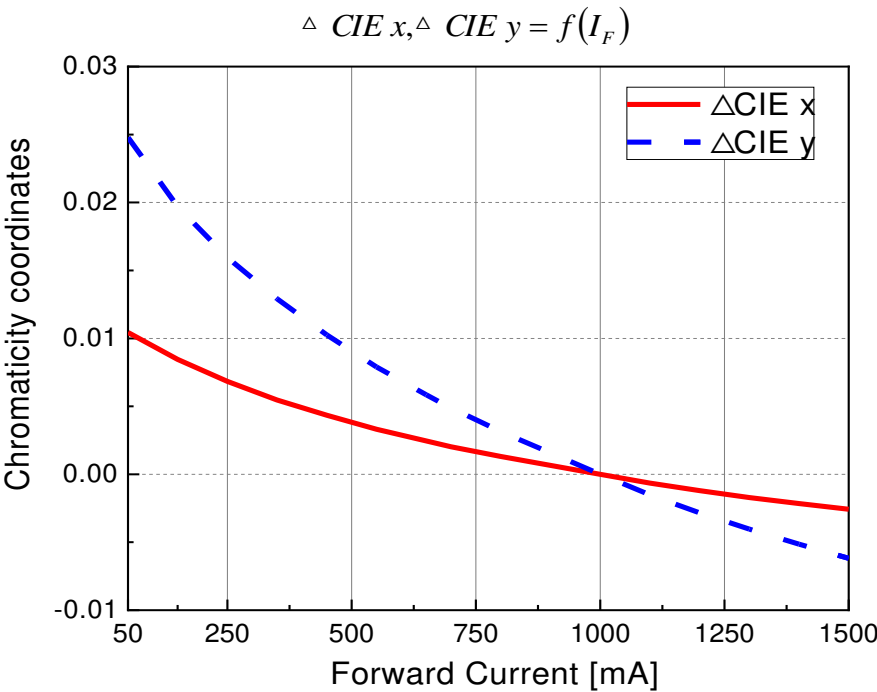
@ Ts = 25°C

$$\Phi_V / \Phi_V (1000mA) = f(I_F)$$



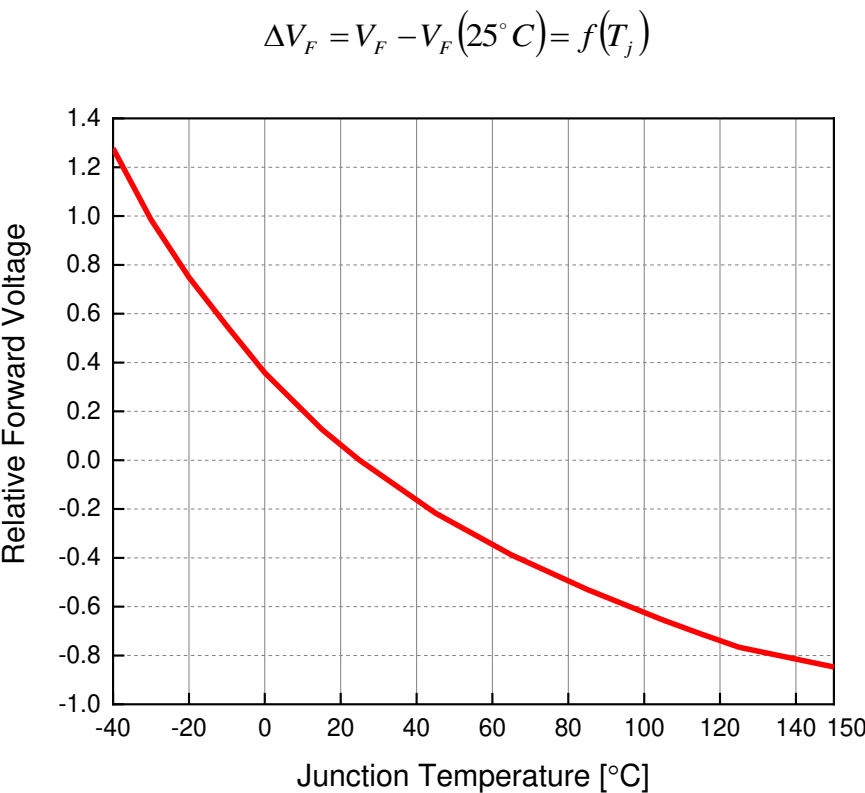
Chromaticity Coordinates Shift vs. Forward Current

@ Ts = 25°C



Relative Forward Voltage vs. Junction Temperature

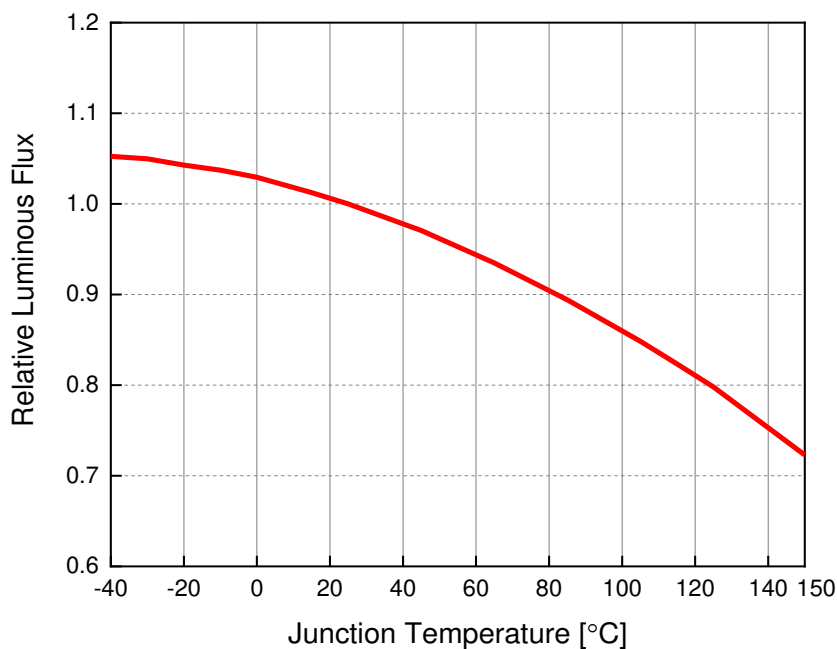
@ IF=1000mA



Relative Luminous Intensity vs. Junction Temperature

@ $I_F=1000\text{mA}$

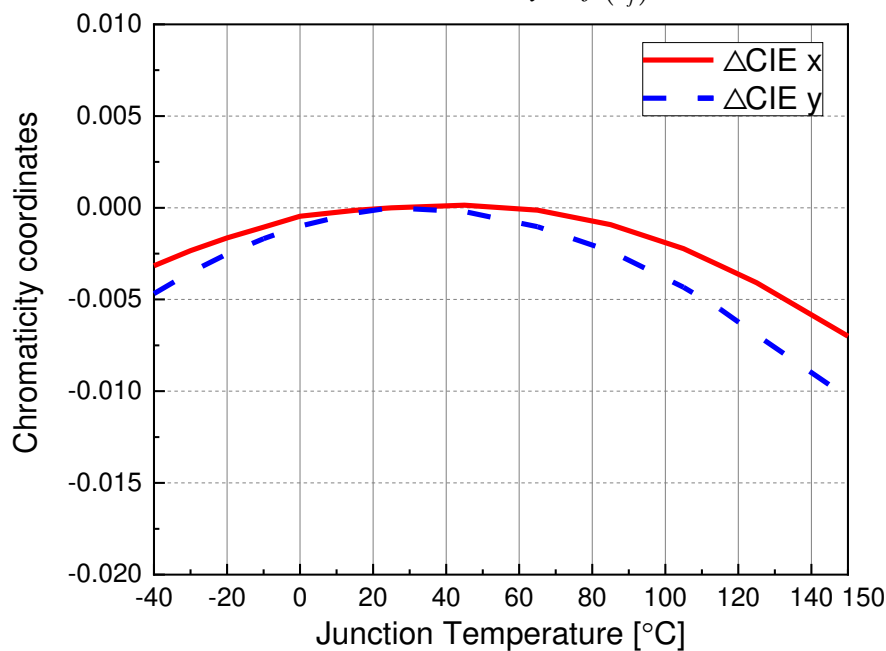
$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j)$$



Chromaticity Coordinates Shift vs. Junction Temperature

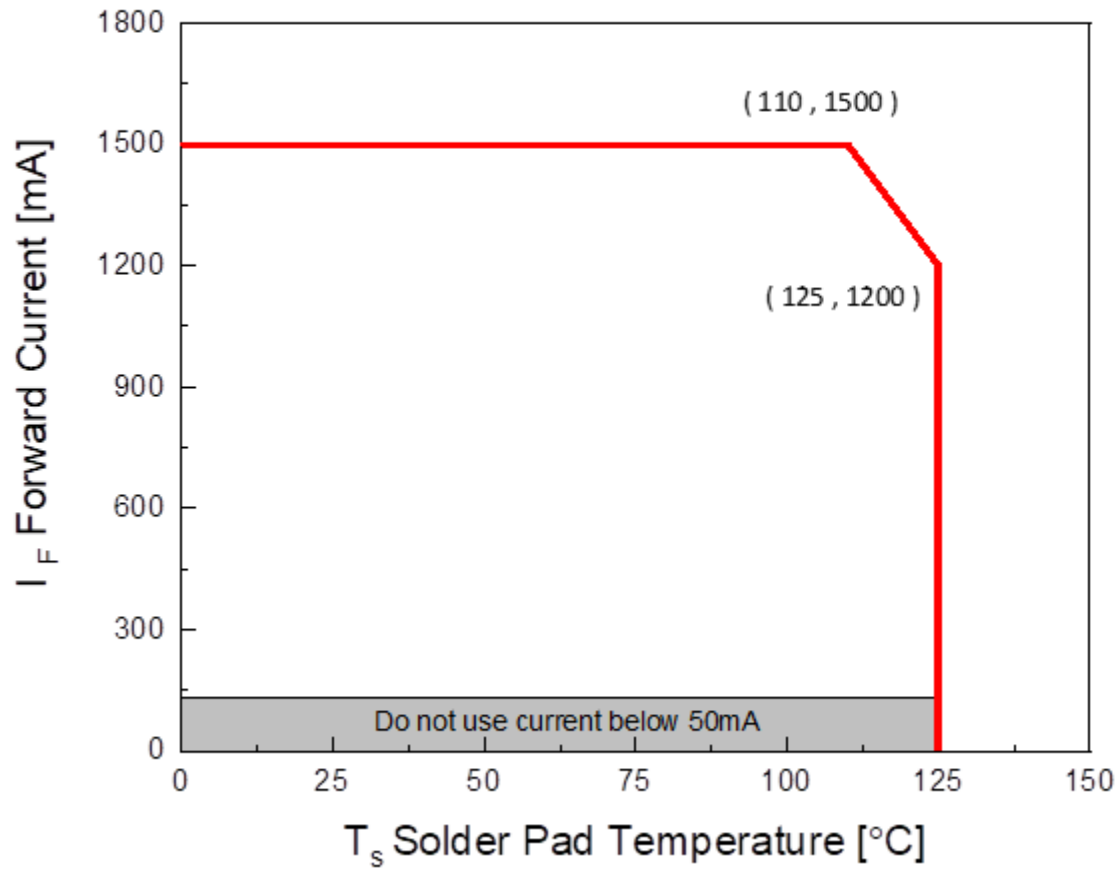
@ $I_F=1000\text{mA}$

$$\Delta CIE\ x, \Delta CIE\ y = f(T_j)$$



Forward Current Derating Curve

$$I_F = f(T_s)$$



4. Binning Information

Luminous Intensity Bins

Group Bin	Bin	Minimum Luminous Flux (lm)	Maximum Luminous Flux (lm)
E	7	1500	1600
	8	1600	1700
	9	1700	1800
F	0	1800	1900
	1	1900	2000

Notes:

1. Luminous flux measurement tolerance: $\pm 8\%$.
2. Test current: Typical forward current.
3. Current pulse time: 25ms

Forward Voltage Bins

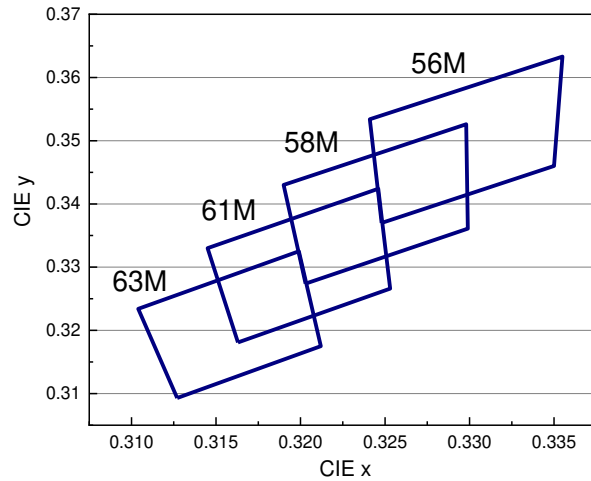
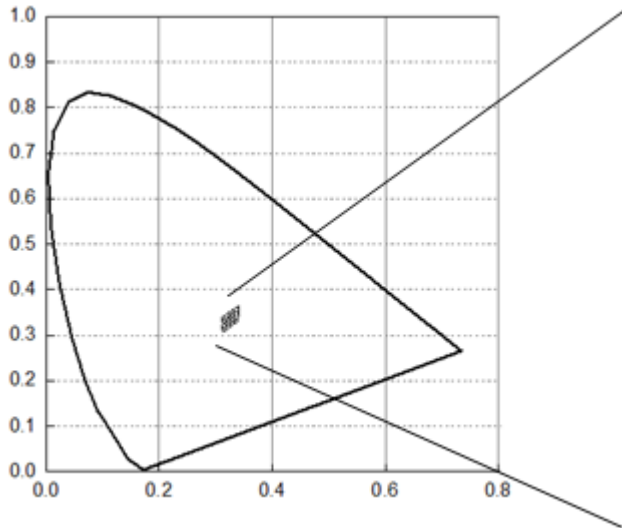
Bin code	Min Forward Voltage [V]	Max Forward Voltage [V]
4A	11.60	12.80
4B	12.80	14.00
4C	14.00	15.20

Notes:

1. Forward Voltage measurement tolerance: $\pm 0.05V$.
2. Test current: Typical forward current
3. Current pulse time: 25ms

Color Bin Structure

ECE Bin Structure



Cool White Bin Coordinates

Bin	CIE x	CIE y
63M	0.3127	0.3093
	0.3212	0.3175
	0.3199	0.3325
	0.3104	0.3234

Bin	CIE x	CIE y
61M	0.3163	0.3181
	0.3253	0.3266
	0.3246	0.3424
	0.3145	0.3330

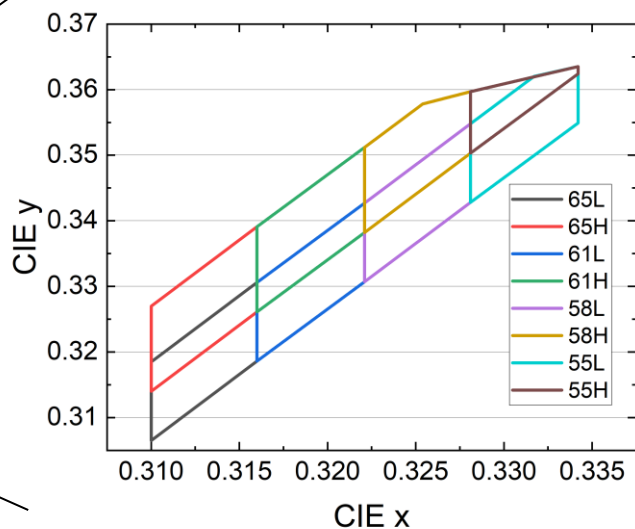
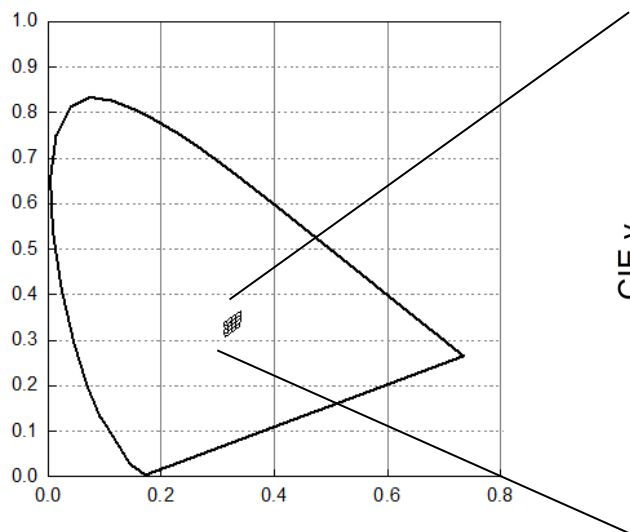
Bin	CIE x	CIE y
58M	0.3203	0.3274
	0.3299	0.3361
	0.3298	0.3526
	0.319	0.343

Bin	CIE x	CIE y
56M	0.3248	0.337
	0.335	0.346
	0.3355	0.3633
	0.3241	0.3534

Notes:

1. Color coordinates measurement tolerance: ± 0.005
2. Test current: Typical forward current.
3. Current pulse time: 25ms

Color Bin Structure



Cool White Bin Coordinates

Bin	CIE x	CIE y
65L	0.3100	0.3065
	0.3100	0.3185
	0.3160	0.3306
	0.3160	0.3186

Bin	CIE x	CIE y
65H	0.3100	0.3140
	0.3100	0.3270
	0.3160	0.3391
	0.3160	0.3261

Bin	CIE x	CIE y
61L	0.3160	0.3186
	0.3160	0.3306
	0.3221	0.3427
	0.3221	0.3307

Bin	CIE x	CIE y
61H	0.3160	0.3261
	0.3160	0.3391
	0.3221	0.3512
	0.3221	0.3382

Bin	CIE x	CIE y
58L	0.3221	0.3307
	0.3221	0.3427
	0.3281	0.3548
	0.3281	0.3428

Bin	CIE x	CIE y
58H	0.3221	0.3382
	0.3221	0.3512
	0.3254	0.3578
	0.3281	0.3597
	0.3281	0.3503

Bin	CIE x	CIE y
55L	0.3281	0.3428
	0.3281	0.3548
	0.3317	0.3620
	0.3342	0.3635
	0.3342	0.3549

Bin	CIE x	CIE y
55H	0.3281	0.3503
	0.3281	0.3597
	0.3342	0.3635
	0.3342	0.3624

Notes:

1. Color coordinates measurement tolerance: ± 0.005
2. Test current: Typical forward current
3. Current pulse time: 25ms

5. Part Number

ALFS4J-C010001H-AM

Part number is designated with below details.

ALFS = Product family name.

4 = chip number

H = Product type

C = Color^[1]

0 = CRI (N/A=0 ; >70=7 ; >80=8 ; >90=9)

1000 = Test current [mA]

1 = internal code

H = Brightness Level

AM = Automotive application

Note

[1] Color :

Symbol	Description
C	Cool White
N	Neutral White
W	Warm White
PA	Phosphor Converted Amber
PR	Phosphor Converted Red
UB	Blue
IB	Ice Blue
SB	Sky Blue
UP	Purple
UG	Green
UY	Yellow
UYG	Brilliant Yellow Green
UPG	Pale Green
UA	Amber
UR	Red
SR	Super Red
RGB	RGB-Color

6. Ordering Information

ALFS4J-C010001H-ABCDEFGHIJKLMN-OP-AM

Part Number of the ALFS1H	Order Code
ALFS4J-C010001H-AM	ALFS4J-C010001H- ABCDEFGHIJKLMN - OP -AM

Order code contains information with below details :

ABCDEF = min/max wavelength or CCT

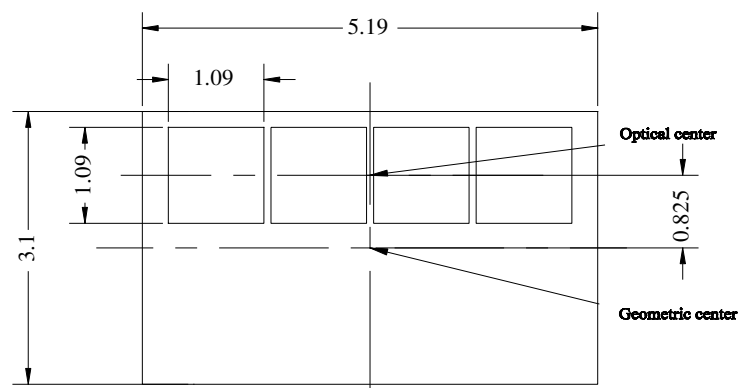
GHIJ = min./max. luminous flux in [lm] or luminous intensity in [mcd]

KLMN = min./max. forward voltage

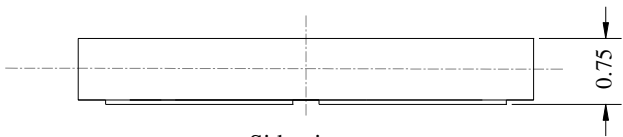
OP = internal code

AM = Automotive Application

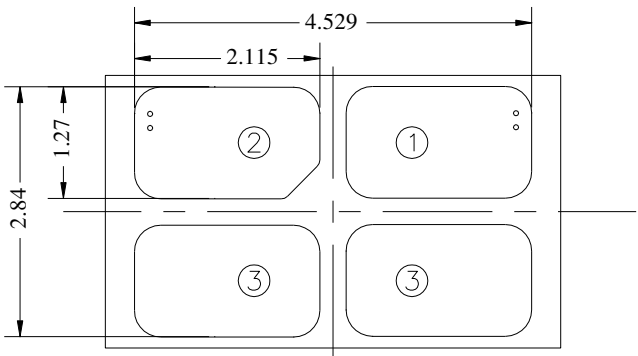
7. Mechanical Dimension



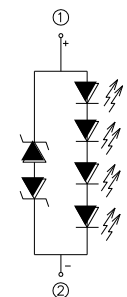
Top view



Side view



Bottom view



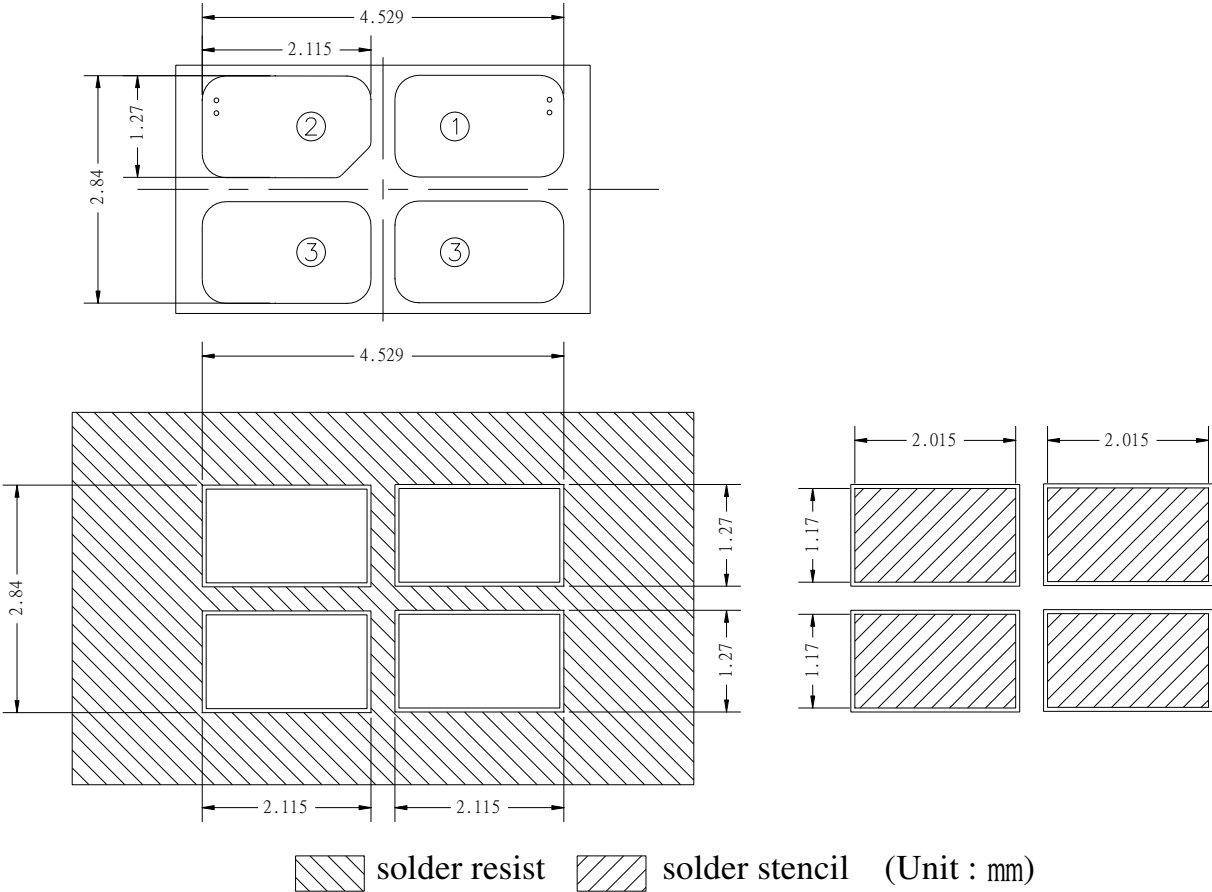
Polarity

①	Anode
②	Cathode
③	Thermal pad

Notes:

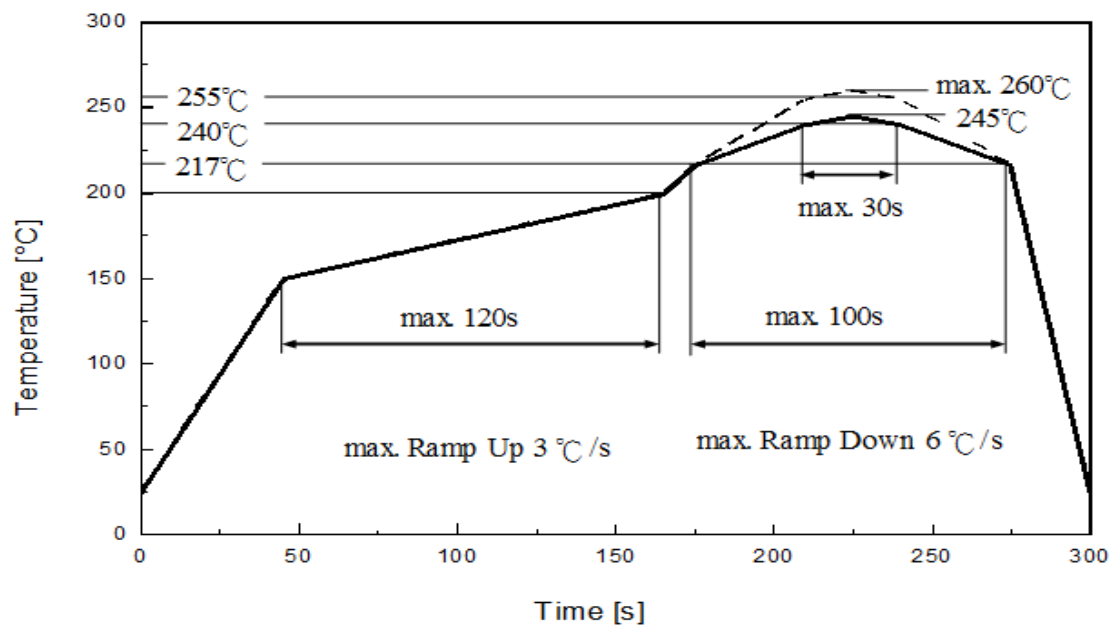
- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are $\pm 0.1\text{mm}$.

8. Recommended Soldering Pad



9. Reflow Soldering Profile

Soldering Condition (Reference: IPC/JEDEC J-STD-020D)



Profile Feature	Pb-Free Assembly	Unit
	Recommendation	
Ramp-up rate to preheat 25 °C to 150 °C	3	°C /sec
Time of soaking zone 150 °C to 200 °C	120	sec
Ramp-up rate to peak	3	°C /sec
Liquidus temperature	217	°C
Time above liquidus temperature	100	sec
Peak temperature (max.)	260	°C
Time within 5°C of the specified peak temperature	30	sec
Ramp-down Rate (max.)	6	°C /sec

10. Packaging Information

- Product Labeling

RoHS

Pb

EVERLIGHT

5

CPN : XXXXXXXXXXXXXXXXXXXX

XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX

P/N : XXXXXXXXXXXX

XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX

LOT No:Y150716XXX-XXXXXXXXXX-XXXXXXXXXX

QTY: 0123456789 HUE: XXXXXXXXXXXX

CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX

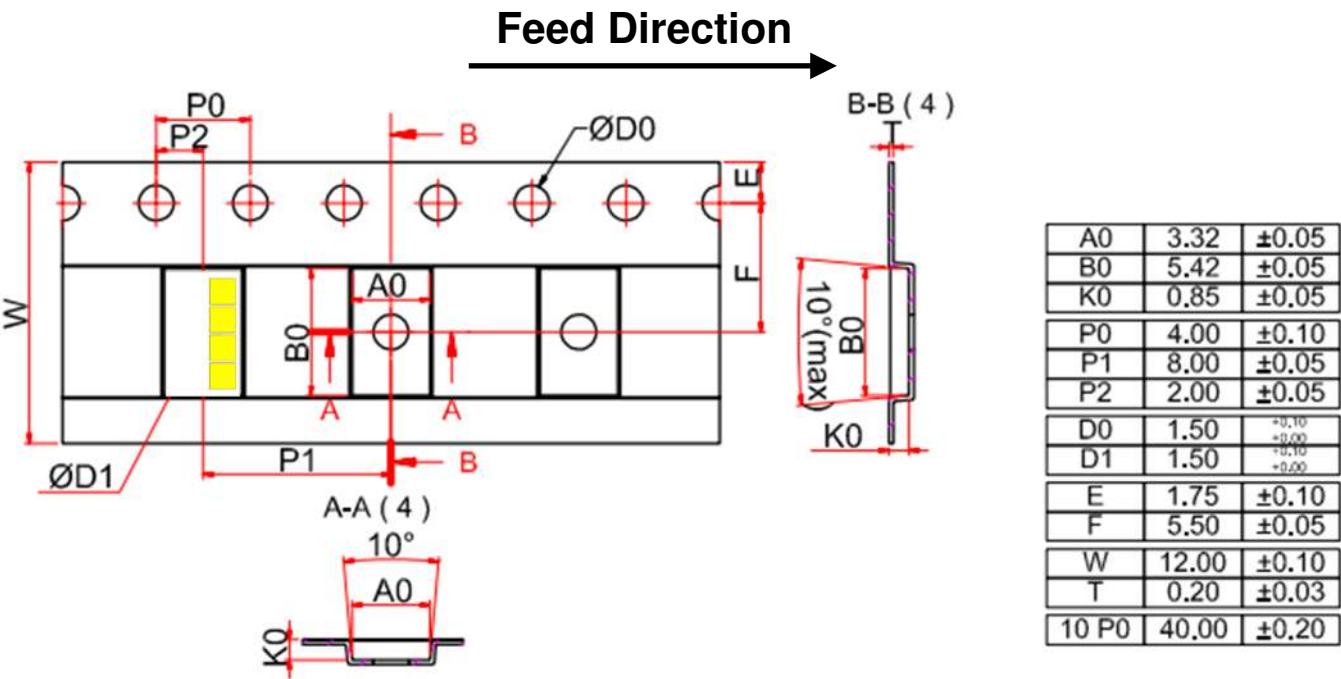
REFERENCE: BTPYYMDDXXXXX

MSL-X MADE IN XXXXXX

- CPN : Customer's Product Number
- P/N : Everlight Part Number
- LOT No : Lot Number
- QTY : Packing Quantity
- HUE : Color Bin
- CAT : Luminous Flux (Brightness) Bin
- REF : Forward Voltage Bin

- Carrier Tape Dimensions as the following

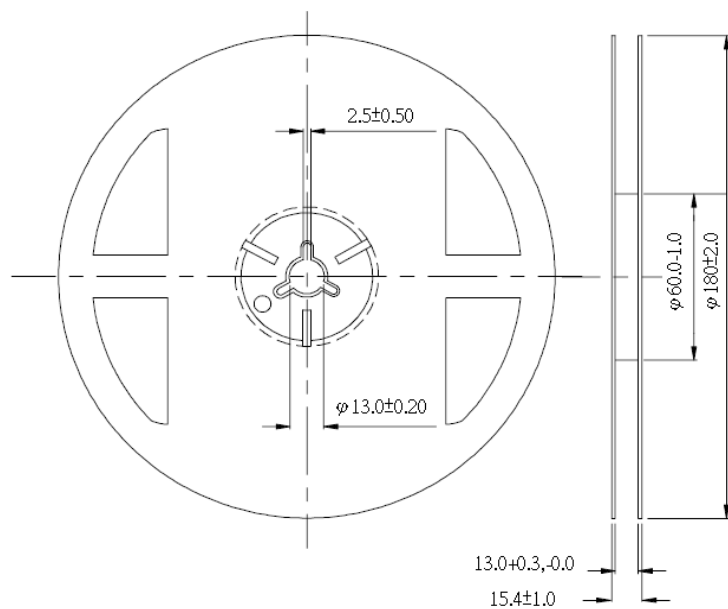
Reel: 1000pcs, MOQ>100pcs(has to be a multiple of 100pcs)



Notes:

1. Dimensions are in millimeters.

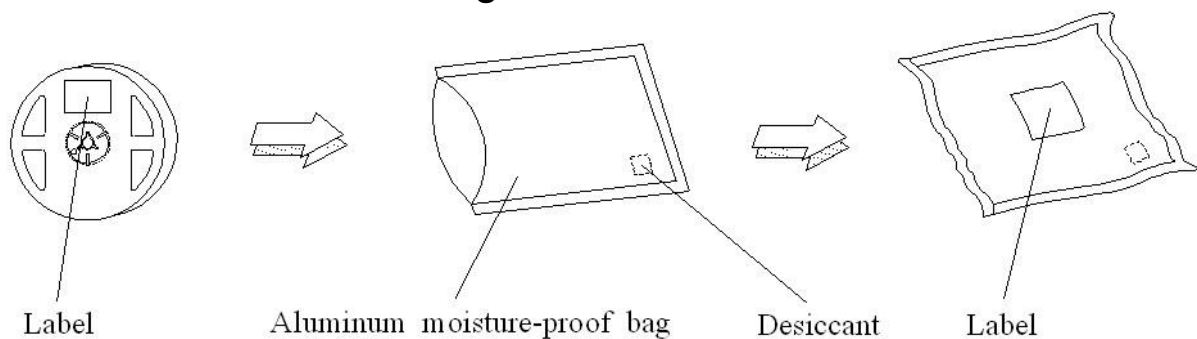
• Reel Dimensions



Notes:

1. Dimensions are in millimeters.

• Moisture Resistant Packing Process



11. Precaution for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (burn out will happen).

2. Assemblies

Do not stack assemblies containing LEDs to prevent damage to the optical surface of LEDs. Forces applied to the optical surface may result in the surface being damaged.

3. Soldering Condition

3.1 When soldering, do not put stress on the LEDs during heating.

3.2 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

12. Sulfur Test Criteria

Products	Failure Criteria			
Exterior Lighting products	Luminous Flux +/-20%, forward voltage +/-10%, color coordinates x,y +/-0.01, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria			
Interior lighting products	Luminous Flux +/-30% or +/-50% for some application, forward voltage +/-10%, color coordinates x,y +/-0.02, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria			
Grade of H2S and FMG test	Please refer to the table as below. As for discolor, please refer to the Frame blackening after Grade of H2S and FMG test defect under Everlight's inspection criteria			
H2S test	Grade A0	Grade A1	Grade B0	Grade B1
Class A	Pass ΔIV , $\Delta Color$, ΔVF criteria No discoloration	Pass ΔIV , $\Delta Color$, ΔVF criteria Discoloration		
Class B			Pass ΔIV , $\Delta Color$, ΔVF criteria No discoloration	Pass ΔIV , $\Delta Color$, ΔVF criteria Discoloration

Class for H2S Test & FMG	Description	
	H2S	FMG
Class A	15 ppm with duration 336 h at 40 °C and 90% RH.	Duration 500 h at 25 °C and 75% RH. H2S concentration: 10ppb SO2 concentration: 200ppb NO2 concentration: 200ppb Cl2 concentration: 10ppb
Class B	10 ppm with duration 500 h at 25 °C and 75% RH.	

Grade for H2S Test	Description
0	No discoloration
1	Discoloration

Revision History

Current version : July, 18, 2025

Issue No: DHE-0004348

Version: 3

Created by: Chris Chuang

Rev.	Subjects (major change in previous version)	Modified date
1	Standard data sheet	2024/03/26
2	Update Rth data 、 CIE BIN Data	2024/05/30
3	Update Color 、 Carrier Tape Dimensions	2025/7/18